TPS61088 reference design

Designator	Oursetitur	Value	Description	DeskowsDeference	DeutNumber	Manufacturar
Designator !PCB	Quantity	Value	Description Printed Circuit Board	PackageReference	PartNumber PMP9772	Manufacturer
есь C1, C16	2	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X5R, 0402	0402	GRM155R61C104KA88	Any MuRata
01, 010	2	0.101	CAF, CERNI, 0.101, 100, 17-1076, ASIR, 0402	0402	D	INUITALA
C3	1	1uF	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603	0603		MuRata
					D	
C4, C5, C6	3	22uF	CAP, CERM, 22 µF, 16 V, +/- 10%, X5R, 1206	1206	GRM31CR61C226KE15	MuRata
					L	
C7, C15	2	4.7uF	CAP, CERM, 4.7uF, 10V, +/-10%, X5R, 0603		0603ZD475KAT2A	AVX
C8	1	0.01uF	CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0402	0402	GRM155R71C103KA01	MuRata
					D	
C9, C10	2	22uF	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 0805	0805	C2012X5R0J226M	TDK
C13	1	100pF	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402	GRM1555C1H101JA01 D	MuRata
C14	1	10uF	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0603	0603	C1608X5R1A106M	TDK
C17	1	0.047uF	CAP, CERM, 0.047 µF, 16 V, +/- 10%, X7R, 0402	0402		MuRata
					D	
C?	1	680uF	CAP, TA, 680 μF, 6.3 V, +/- 10%, 0.045 ohm, SMD	7343-43	TPSE687K006R0045	AVX
H1, H2, H3,	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips	Screw	NY PMS 440 0025 PH	B&F Fastener Supply
H4			panhead			
H5, H6, H7, H8	4		Standoff, Hex, 0.5"L #4-40 Nylon	Standoff	1902C	Keystone
J1, J2, J3	3		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
J4	1		Header, 100mil, 4x1, Gold, TH	4x1 Header	TSW-104-07-G-S	Samtec
JP2	1		Header, 100mil, 2x1, Tin, TH	Header, 2 PIN,	PEC02SAAN	Sullins Connector Solutions
				100mil, Tin		
JP3	1		Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin	PEC03SAAN	Sullins Connector Solutions
L1	1	680nH	Inductor, Shielded Drum Core, Metal Composite, 680 nH, 15.4 A, 0.00384 ohm, SMD	9.5x8.7mm	CDMC8D28NP-R68MC	Sumida
L2	1	6.8uH	Inductor, Wirewound, Ferrite, 6.8 µH, 0.65 A, 0.45 ohm, SMD	3.0x0.9x3.0mm	LQH3NPN6R8NG0	MuRata
R1	1	49.9	RES, 49.9 ohm, 1%, 0.063W, 0402	0402	CRCW040249R9FKED	Vishay-Dale
R2	1	97.6k	RES, 97.6 k, 1%, 0.063 W, 0402	0402	CRCW040297K6FKED	Vishay-Dale
R3	1	56.2k	RES, 56.2 k, 1%, 0.063 W, 0402	0402	CRCW040256K2FKED	Vishay-Dale
R7	1	301k	RES, 301 k, 1%, 0.063 W, 0402	0402	CRCW0402301KFKED	Vishay-Dale
R8	1	3.92k	RES, 3.92 k, 1%, 0.063 W, 0402	0402	CRCW04024K99FKED	Vishay-Dale
R9, R14	2	100k	RES, 100k ohm, 1%, 0.063W, 0402	0402	CRCW0402100KFKED	Vishay-Dale
R10	1	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	RC0402JR-070RL	Yageo America
R13	1	1.00Meg	RES, 1.00 M, 1%, 0.063 W, 0402	0402	CRCW04021M00FKED	Vishay-Dale
SH-JP2, SH- JP3	2	1x2	Shunt, 100mil, Gold plated, Black	Shunt	969102-0000-DA	3M
TP1, TP2,	6	Red	Test Point, TH, Multipurpose, Red	Keystone5010	5010	Keystone
TP3, TP4,	Ū					
TP5, TP6						
U1	1		13.2-V Output, Synchronous Boost Converter with 10-A	RHL0020A	TPS61088RHLR	Texas Instruments
U2	4	TLV61220DBV	Switch, RHL0020A			TI
02	1		IC, High Efficient, Tiny 1Cell Lilon or 1-3 Cells Alk/Nixx Boost Converter	0-10	TLV61220DBV	"
C2	0	47pF	CAP, CERM, 47 pF, 50 V, +/- 1%, C0G, 0402	0402	GRM1555C1H470FA01	MuRata
02	0		, certai, +/ pr, co v, //- 1/0, coc, 0+02	0102	D	martatu
C11	0	220uF	CAP, TA, 220 μF, 10 V, +/- 10%, 0.15 ohm, SMD	7343-31		AVX
C12	0	1000pF	CAP, CERM, 1000 pF, 100 V, +/- 10%, X7R, 0603	0603		MuRata
		·	· · · · · · · · · · · · · · · · · · ·		D	
C18	0	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X5R, 0402	0402	GRM155R61C104KA88	MuRata
					D	

Notes:

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